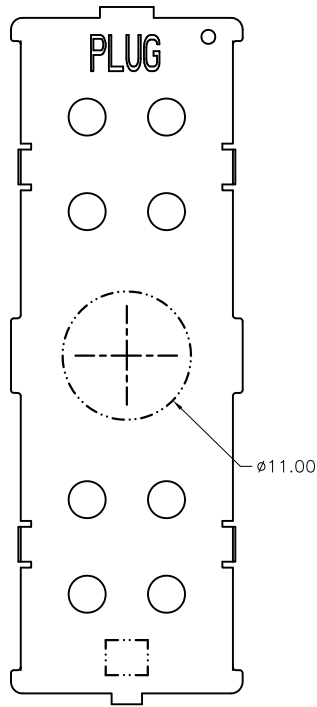
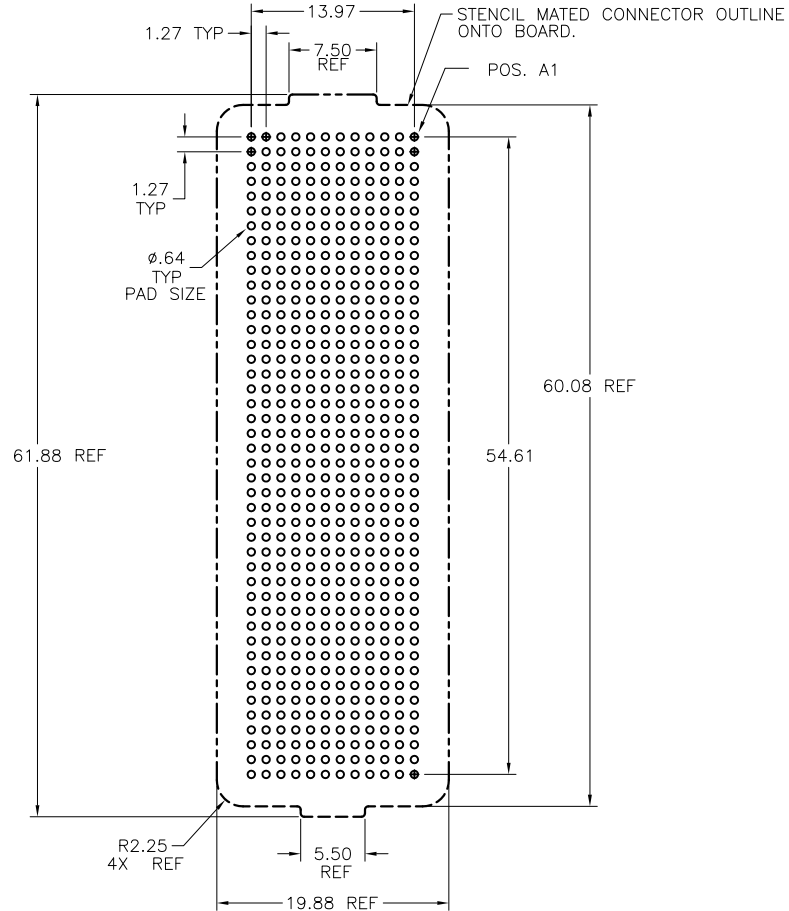


mat'l. code				surface		tolerance		projection		product family	
SEE NOTE 1				ASME Y14.5		ASME Y14.5		ASME Y14.5		MEG-Array	
ltr	ec'n no	dr	date	tolerances unless otherwise specified		angles		MM		title	
A	V03-1102	LP	2003-10-20			X ±3				Omm PLUG ASSY	
B	V04-0940	VS	2004-10-13			XX ±10				12 X 44 = 528 POS.	
C	V06-0560	LP	2006-07-17			O' ±2'		XXX ±0.50		scale 1:1	
D	V12-0031	SJ	2012-08-03	dr	D.INGRAM	2003-02-05				sheet 1 of 4 size	
E	V12-0050	DCH	2012-11-20	enfr	D.WHITING	2003-02-05				dwg no	
				chr	D.WHITING	2003-02-05				10022671	
				appd	D.WHITING	2003-02-05				A4	
sheet	revision	E	E	E	E			type		CUSTOMER Drawing	
index	sheet	1	2	3	4						



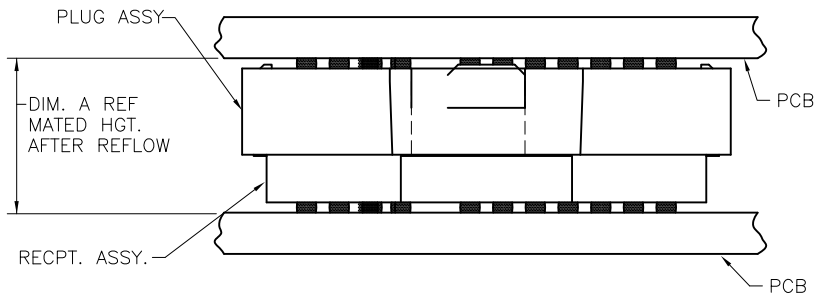
VACUUM AREA FOR OPTIONAL PICK UP CAP



BOARD PATTERN
SCALE 2/1

mat'l. code		surface		tolerance		projection		product family							
SEE NOTE 1		ASME Y14.5		ASME Y14.5				MEG-Array							
ltr	ecn no	dr	date	tolerances unless otherwise specified				title							
E				angles	<table border="1"> <tr><td>X</td><td>+3</td></tr> <tr><td>XX</td><td>+10</td></tr> <tr><td>XXX</td><td>+050</td></tr> </table>	X	+3	XX	+10	XXX	+050	MM		0mm PLUG. ASSY 12 X 44 = 528 POS.	
X	+3														
XX	+10														
XXX	+050														
				0' ±2'	scale 1:1										
		dr	D. INGRAM	2003-02-05											
		engr	D. WHITING	2003-02-05											
		chr	D. WHITING	2003-02-05											
		appd	D. WHITING	2003-02-05	dwg no 10022671 type CUSTOMER Drawing		sheet 2 of 4	size A4							
sheet index	revision sheet														

PRODUCT NUMBER	PICK-UP CAP (NATURAL OR BLACK IN COLOR)	CONTACT PLATING AND THICKNESS	SOLDER BALL	NOTES
10022671-002	YES	15µ" (.38µm) Au	SnPb	
10022671-002LF	YES	15µ" (.38µm) Au	LEAD FREE	8
10022671-092	YES	15µ" (.38µm) GXT	SnPb	
10022671-092LF	YES	15µ" (.38µm) GXT	LEAD FREE	8
10022671-102	YES	30µ" (.76µm) Au	SnPb	
10022671-102LF	YES	30µ" (.76µm) Au	LEAD FREE	8
10022671-192	YES	30µ" (.76µm) GXT	SnPb	
10022671-192LF	YES	30µ" (.76µm) GXT	LEAD FREE	8
10022671-202	YES	50µ" (1.27µm) Au SPECIAL	SnPb	4 AND 5
10022671-202LF	YES	50µ" (1.27µm) Au SPECIAL	LEAD FREE	4, 5, and 8
10022671-292	YES	50µ" (1.27µm) GXT SPECIAL	SnPb	4 AND 5
10022671-292LF	YES	50µ" (1.27µm) GXT SPECIAL	LEAD FREE	4, 5 AND 8
10022671-302	YES	15µ" (.38µm) Au SPECIAL	SnPb	9
10022671-302LF	YES	15µ" (.38µm) Au SPECIAL	LEAD FREE	8 & 9
10022671-402	YES	30µ" (.76µm) Au SPECIAL	SnPb	9
10022671-402LF	YES	30µ" (.76µm) Au SPECIAL	LEAD FREE	8 & 9
10022671-502	YES	Au SPECIAL	SnPb	4, 5 & 9
10022671-502LF	YES	Au SPECIAL	LEAD FREE	4, 5, 8 & 9



DIM. A	RECPT. ASSY. P/N	PLUG ASSY. P/N
6.0	10026846-X01	10022671-X02

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.



END VIEW - MATED CONNECTORS SCALE NONE

mat'l. code		surface		tolerance		projection		product family	
SEE NOTE 1		ASME Y14.5		ASME Y14.5				MEG-Array	
ltr	ecr no	dr	date	tolerances unless otherwise specified		MM		title	
E				angles	X ±3			0mm PLUG ASSY	
				0° ±2'	.XX ±10	scale 1:1		12 X 44 = 528 POS.	
				appd	XXX ±050			dwg no	
				dr	D.INGRAM	2003-02-05		sheet 3 of 4	
				engr	D.WHITING	2003-02-05		size	
				chr	D.WHITING	2003-02-05		10022671	
				appd	D.WHITING	2003-02-05		A4	
sheet index	revision sheet							type CUSTOMER Drawing	

NOTES:

1. **MAT'L:**
HOUSING: LCP
CONTACT: COPPER ALLOY
PLATING:
 CONTACT: (SEE TABLE ON SHEET3)
 SOLDER BALL: (SEE TABLE ON SHEET3)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu
2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
4. PLATING FOR INDICATED -2XX SERIES PRODUCT NUMBER MEET THE REQUIREMENTS OF GR-1217-CORE, CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY).
5. PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
6. **KNIT LINE:** SLIGHT VISIBLE MARKS (USUALLY A LINE) INDICATING THE DIRECTION AND MEETING POINT OF PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.
7. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
8. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

11. A  SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

mat'l. code		surface		tolerance		projection		product family	
SEE NOTE 1		ASME Y14.5		ASME Y14.5				MEG-Array	
ltr	ecn no	dr	date	tolerances unless otherwise specified		MM		title	
E				angles	X ±3	←		0mm PLUG ASSY	
				linear	.XX ±10	→		12 X 44 = 528 POS.	
				0° ±2'	XXX ±050	scale 1:1		dwg no	
		dr	D.INGRAM	2003-02-05			sheet 4 of 4		size
		engr	D.WHITING	2003-02-05			10022671		A4
		chr	D.WHITING	2003-02-05			type		CUSTOMER Drawing
		appd	D.WHITING	2003-02-05					
sheet index	revision sheet								